AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Serial Number: 10/774,869

Filing Date: February 9, 2004
Title: UNDERFILL PROCESS FOR FLIP-CHIP DEVICE

Assignee: Intel Corporation

IN THE SPECIFICATION

Please amend the specification as follows:

The paragraph beginning at page 1, after the title, is amended as follows:

RELATED APPLICATIONS

The application is a divisional of U.S. Patent Application Serial No. 10/032,115, filed December 21, 2001, now issued as U.S. Patent No. 6,703,299, which is incorporated herein by reference.